

SF21G THRU SF28G

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SF21G THRU SF28G

2.0A Axial Leaded Super Fast Rectifiers-50-600V

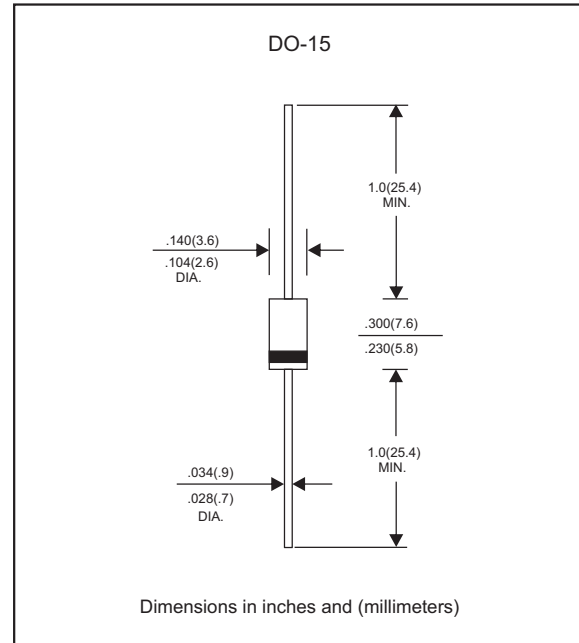
Features

- Axial lead type devices for through hole design
- High current capability.
- Superfast recovery time for switching mode application.
- High surge current capability.
- Glass passivated chip junction structure.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. SF21G-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-15
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 0.40 gram

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = 55°C	I_o			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC method)	I_{FSM}			60	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^{\circ}\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM}$ $T_J = 125^{\circ}\text{C}$				150	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_j		60		pF
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	t_{rr}^{*5} (ns)	Operating temperature $T_J, (^{\circ}\text{C})$
SF21G	50	35	50	0.95	35	-55 to +150
SF22G	100	70	100			
SF23G	150	105	150			
SF24G	200	140	200			
SF25G	300	210	300	1.25	35	-55 to +150
SF26G	400	280	400			
SF27G	500	350	500			
SF28G	600	420	600	1.70	35	-55 to +150

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I_F=2.0\text{A}$
- *5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Rating and characteristic curves (SF21G THRU SF28G)

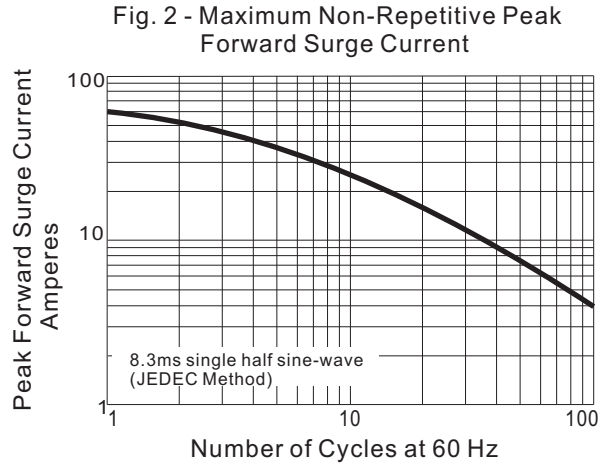
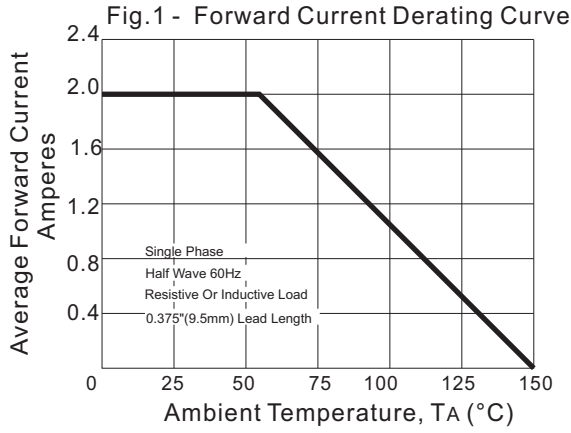


Fig. 3 - Typical Instantaneous Forward Characteristics

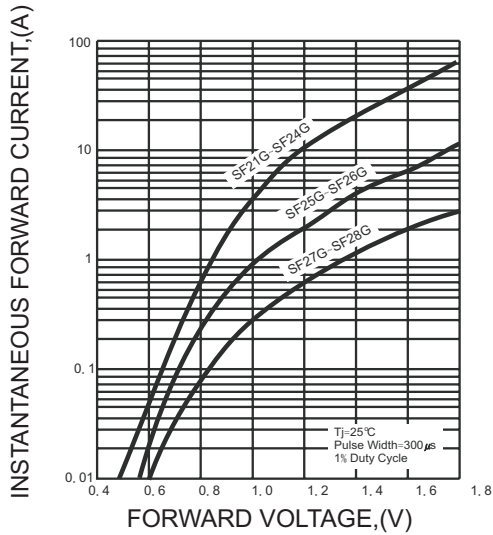


Fig. 4 - Typical Instantaneous Reverse Characteristics

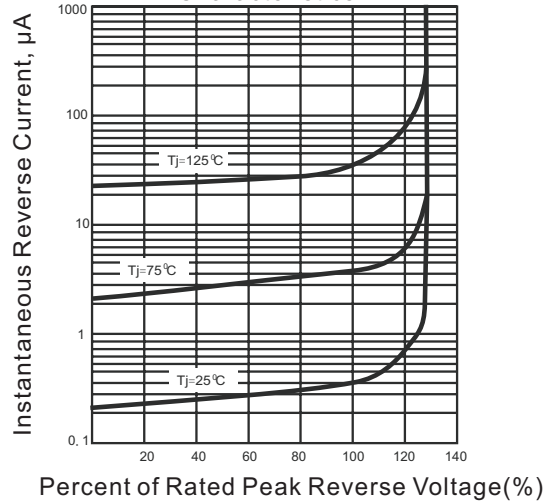


Fig. 5 - Typical Junction Capacitance

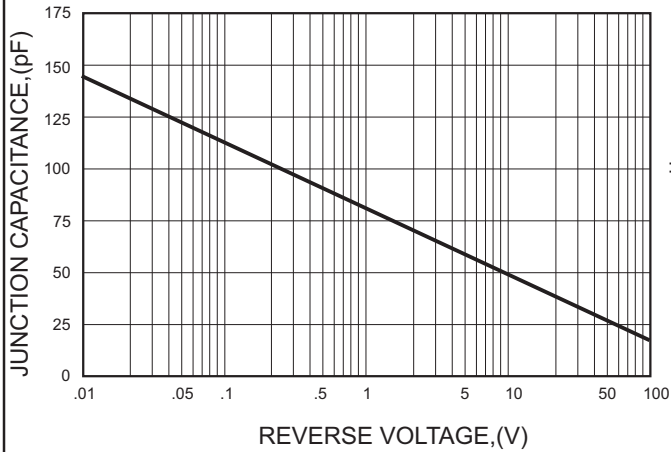
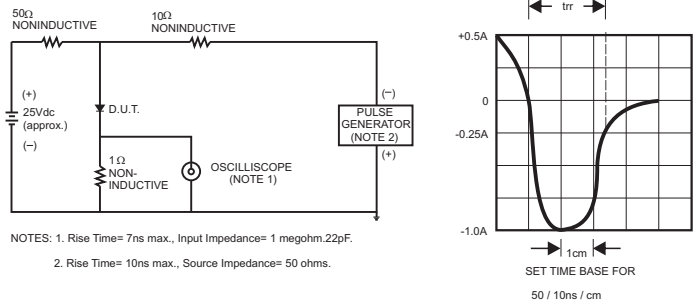


Fig. 6 - Test Circuit Diagram and Reverse Recovery Time Characteristic



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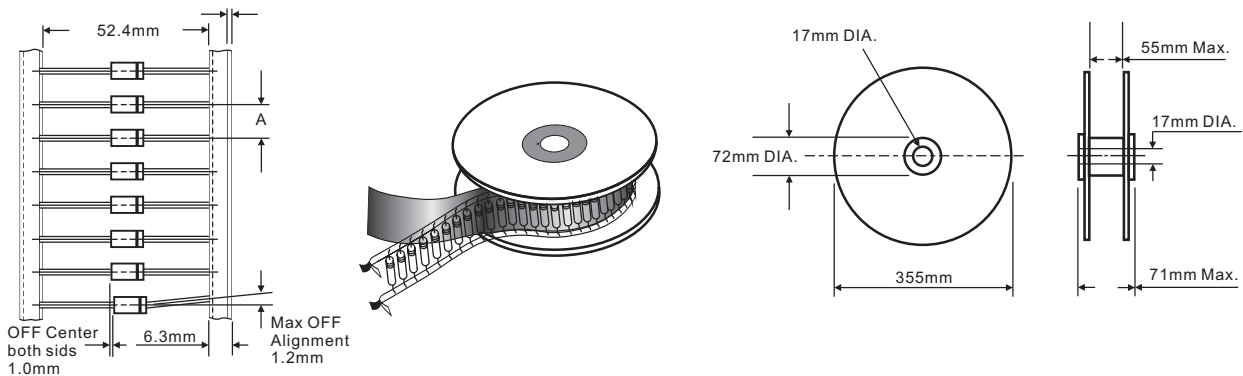
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SF21G	SF21G
SF22G	SF22G
SF23G	SF23G
SF24G	SF24G
SF25G	SF25G
SF26G	SF26G
SF27G	SF27G
SF28G	SF28G

Taping & bulk specifications for AXIAL devices



REEL PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	4,000	5 mm	380 * 340 * 370	16,000	9.9

AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	3,000	260 * 83 * 160	440 * 270 * 340	30,000	14.3

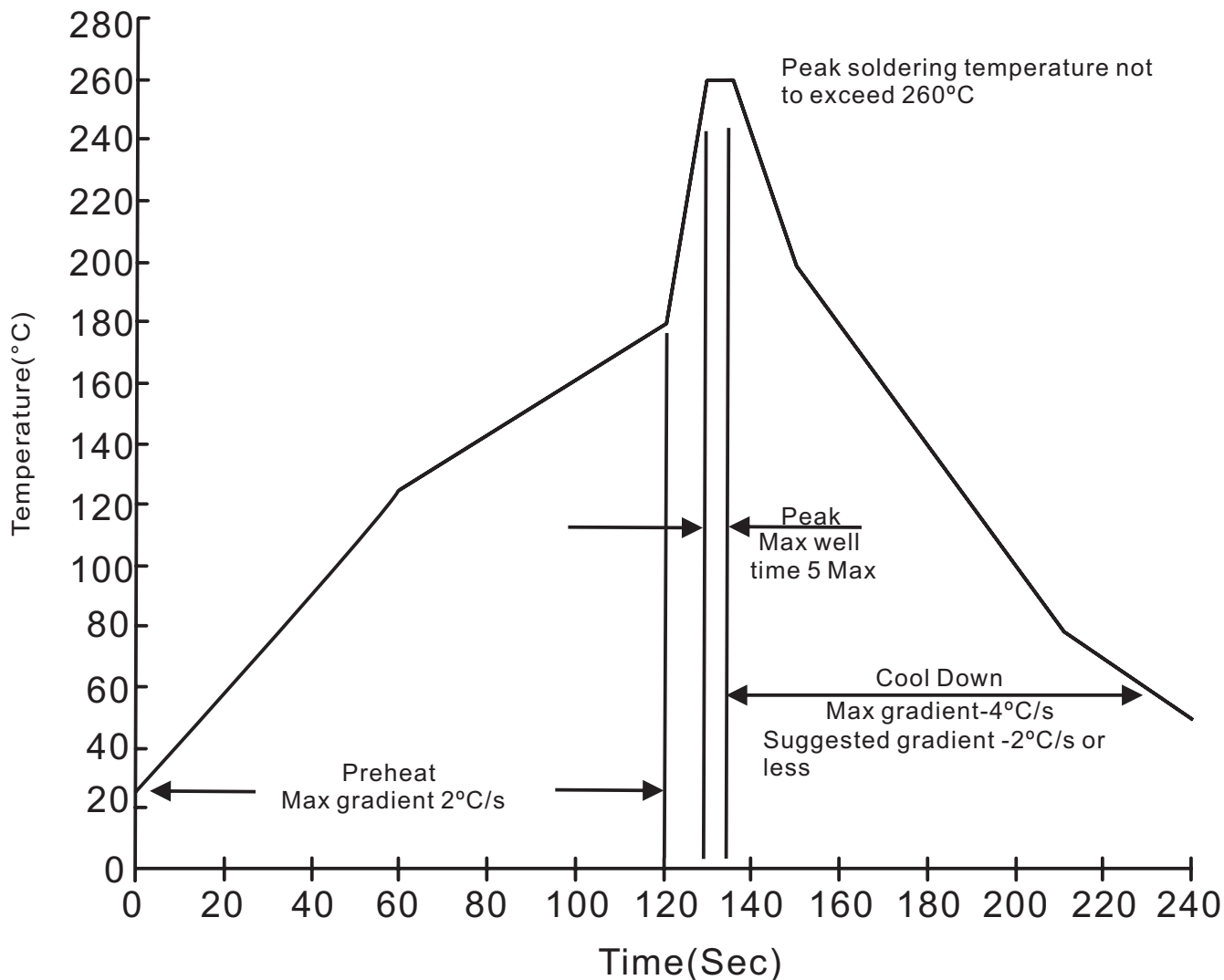
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BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	500	194 * 84 * 20	465 * 220 * 260	25,000	12.9

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



SF21G THRU SF28G**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec}$. immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	1.0kg in axial lead direction for 10 sec. $I_F=I_O$	MIL-STD-202F METHOD-211A
4. Bend Lead	1.0kg weight applied to each lead bending arc $90^{\circ}\pm 5^{\circ}$ for 3 times	MIL-STD-202F METHOD-211A
5. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs. $T_A = 25^{\circ}\text{C}$, $I_F = I_O$	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life	On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1036
8. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Forward Surge	8.3ms single half sine-wave one surge.	MIL-STD-750D METHOD-4066-2
11. Humidity	at $T_A=85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
12. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031